



(非累積公差)  
 推奨基板取付け穴寸法 (コネクタ搭載面)  
 RECOMEND PC BOARD HOLL PATTERN (NOT ACCUMULATE TOLERANCE)  
 PC BOARD THICKNEES; 1.6±0.1 (PC 基板厚; 1.6±0.1)

- 注記
- ① 材料; ハウジング; ガラス入りポリエステル樹脂  
 CONTACT; 銅合金 熱可塑性ポリエステル樹脂  
 リテンションレグ; 銅合金
  - ② めっき; (CONTACT 接触部); ニッケル下地の上に 0.38μMIN 金メッキ
  - ③ めっき; (CONTACT 接触部); ニッケル下地の上に 0.76μMIN 金メッキ
  - ④ めっき; (CONTACT 全面); ニッケル下地の上に 2.0 μMIN スズメッキ
  - ⑤ (リテンションレグとCONTACT半田付け部); ニッケル下地の上に半田メッキ
  - ⑥ めっき; リテンションレグとCONTACT半田付け部  
 : ニッケル下地の上にスズめっき
- NOTES
- ① MATERIAL HOUSING: GLASS FILED POLYESTER  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
  - ② FINISH (CONTACT AREA): 0.38μMIN GOLD PLATED OVER NICKEL
  - ③ FINISH (CONTACT AREA): 0.76μMIN GOLD PLATED OVER NICKEL
  - ④ FINISH (CONTACT): 2.0 μMIN TIN PLATED OVER NICKEL
  - ⑤ FINISH (RETENTION LEG AND CONTACT TAIL): TIN-LEAD  
 PLATED OVER NICKEL
  - ⑥ FINISH (RETENTION LEG): TIN PLATED  
 (CONTACT TAIL) OVER NICKEL

NUMBER 178137  
 METRIC  
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT  
 PRINT DIST

XY	△6 △4	3-178137-5	
	△6 △3	3-178137-3	
YY	△6 △4	2-178137-5	
	△6 △3	2-178137-3	
XX	△6 △2	2-178137-2	
	△6 △4	1-178137-5	
	△6 △3	1-178137-3	
	△6 △2	1-178137-2	
KEYING LOCATION	KEYING NAME	FINISH	PART NO.

C1	REVISED PER ECO-11-005030	RK	HMR	24MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm <sup>2</sup> (AWG - )		mmφ		DYNAMIC D-3100 3.81 X 7.62 PITCH(H) 6POS. HDR CONN. ASS'Y (KEY;XX,YY,XY)	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	SIZE LOC NUMBER
DR. 1-JULY-'92 Y.TANAKA		DE. 1-JULY-'92 Y.TANAKA		10% ±0.3	A3 J C-178137
CHK. 6-JUL-'92 S.MANABE		APP. 6-JUL-'92 S.MANABE		10% 30% ±0.4	SCALE REV. SHEET
				30% 100% ±0.45	2-1 C1 1 OF 1
				角度 ±3'	